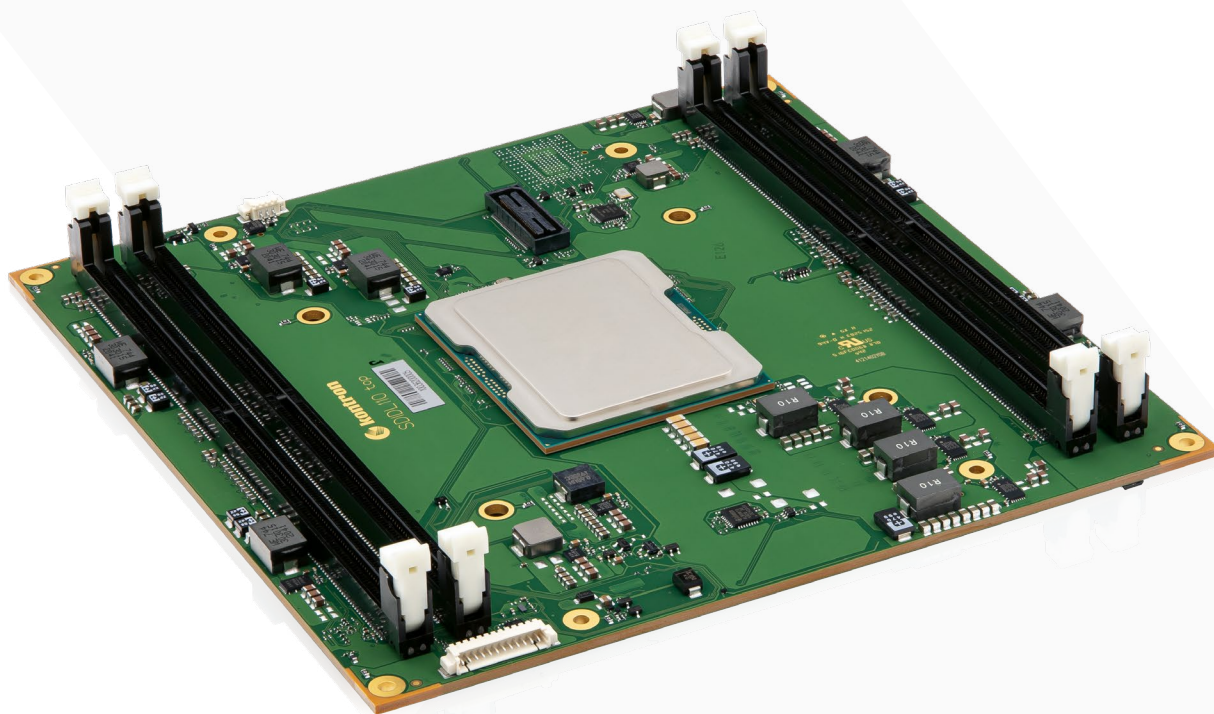




COM+HPC®

COM-HPC®/Server Size D
with Intel® XEON® D-2700 / D-2800 SOC processors

- High-end server-grade platform
- 8x LAN Ports: versatile configurations up to 100G
- High-speed connectivity 32x PCIe 4.0 + 16x PCIe 3.0, SATA, USB 3.0
- Up to 1 TByte NVMe SSD onboard
- Industrial grade versions

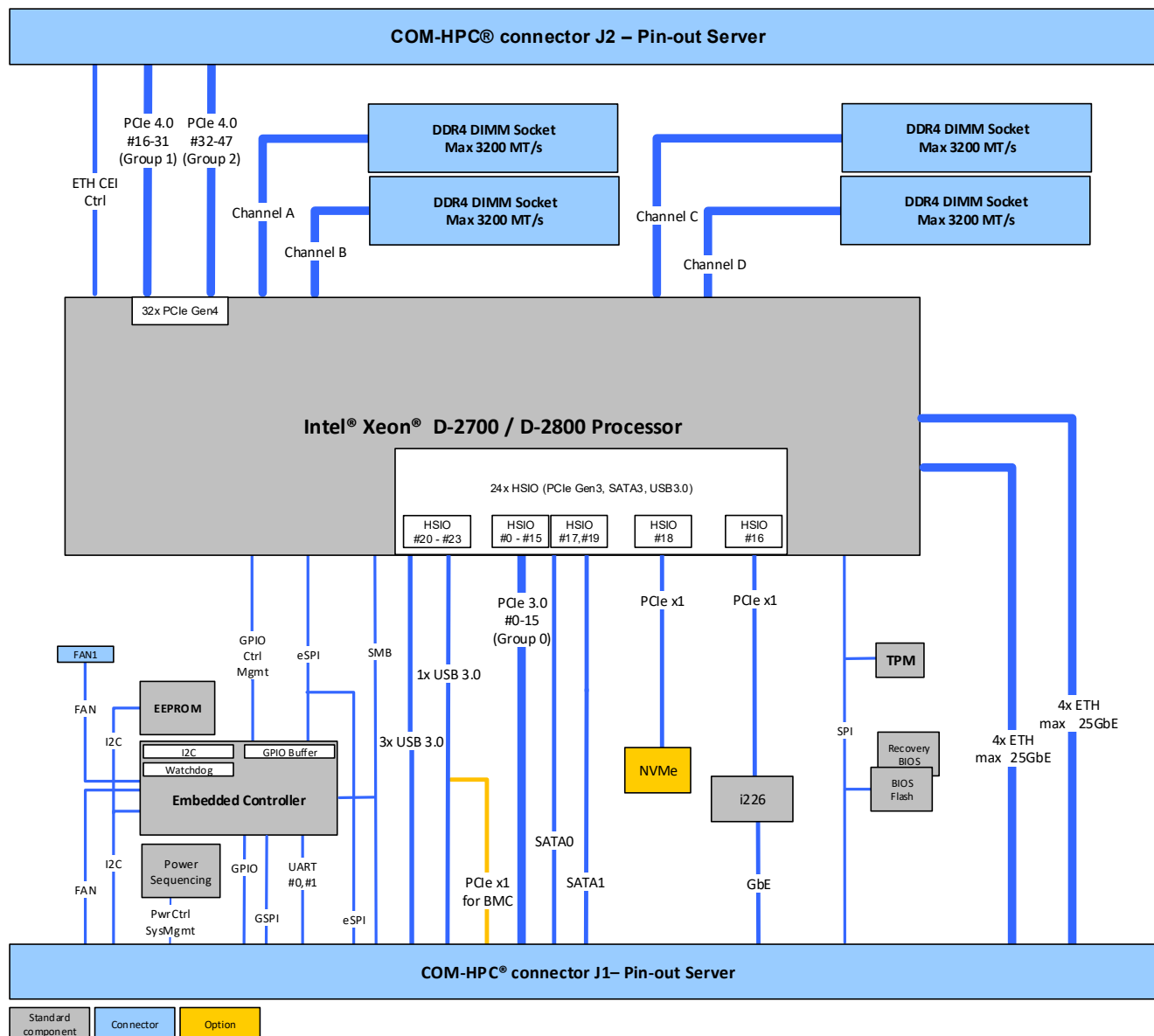
COMPLIANCE	COM-HPC®/Server, Size D
DIMENSIONS	160 mm x 160 mm
CPU (SoC)	Intel Xeon® D-2700 / D-2800 Processor Series For details see table "CPU variants" given below
CHIPSET	-
MAIN MEMORY	4x DDR4 DIMM sockets for up to 128GB LRDIMM
ETHERNET CONTROLLER	Intel® I226-LM/IT Intel® 2x Quad 25GbE LAN integrated in SoC
ETHERNET	1x 1/2.5 Gb Ethernet 8x Ethernet ports supporting versatile configurations: 100GbE/2x 50GbE/4x 25GbE/2x 25GbE + 4x 10GbE/8x 10GbE
STORAGE	2x SATA 6Gb/s
FLASH ONBOARD	Up to 1 TByte NVMe SSD (on request)
PCI EXPRESS®	32x PCIe Gen4 (2 x16, 4 x8, 8 x4) 16x PCIe Gen3 (2 x8, 4 x4, 8 x2)
USB	4x USB 3.0 / USB 2.0
SERIAL	2x serial interface (RX/TX only)
OTHER FEATURES	SPI, eSPI, SMB, Staged Watchdog, RTC
SPECIAL FEATURES	TPM 2.0
FEATURES ON REQUEST	NVMe SSD, 1x PCIe Gen3 for BMC instead of 4th USB3.0
POWER MANAGEMENT	ACPI 6.0
POWER SUPPLY	12V DC
BIOS	AMI UEFI
OPERATING SYSTEM	Linux. Windows 10/11, Windows Server 2022
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +80 °C non-operating Industrial temperature: -40 °C to +80 °C operating, -40 °C to +80 °C non-operating
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)
SUPPORTED MODULES	COMh-sdID xxxxx commercial grade COMh-sdID E2 xxxxx industrial grade

CPU	STD /on request	CORES	TDP, W	IOTG	eTemp	DDR4 1DPC (MT/s)	Ethernet mode	QAT	BASE FREQ (GHZ)	ALL CORE TURBO (GHZ)
D-2796TE	yes	20	118	Yes	Yes	2933	100G	DISABLED	2	2,4
D-2896TER	on request	20	110	Yes	Yes	2933	100G	DISABLED	2	2,5
D-2775TE	yes	16	100	Yes	Yes	2933	100G	DISABLED	2	2,4
D-2752TER	yes	12	77	Yes	Yes	2667	50G	DISABLED	1,8	2,1
D-2733NT	on request	8	80	Yes	No	2667	50G	50G	2,1	2,6
D-2712T	on request	4	65	Yes	No	2667	50G	DISABLED	1,9	2,4
D-2899NT	on request	22	135	No	No	3200	100G	100G	2,2	2,8
D-2798NX	on request	20	126	No	No	2933	100G	100G Inline	2,1	2,6
D-2796NT	yes	20	120	No	No	2933	100G	100G	2	2,5
D-2798NT	on request	20	125	No	No	3200	100G	100G	2,1	2,6
D-2896NT	on request	20	120	No	No	2933	100G	100G	2	2,6
D-2786NTE	on request	18	118	No	Yes	2933	100G	100G	2,1	2,5
D-2777NX	on request	16	116	No	No	2667	100G	100G Inline	2,2	2,7
D-2776NT	on request	16	117	No	No	2933	100G	100G	2,1	2,6
D-2876NT	on request	16	100	No	No	2933	100G	50G	2	2,5
D-2766NT	on request	14	97	No	No	2667	100G	50G	2	2,5
D-2753NT	on request	12	87	No	No	2667	100G	50G	2	2,5
D-2752NTE	on request	12	84	No	Yes	2667	50G	50G	1,9	2,3
D-2757NX	on request	12	107	No	No	2667	50G	50G Inline	2,5	3
D-2745NX	on request	10	96	No	No	2667	50G	50G Inline	2,4	2,9
D-2843NT	on request	10	80	No	No	2667	50G	50G	2	2,6
D-2832NT	on request	8	70	No	No	2667	50G	50G	2,1	2,6
D-2799	on request	20	129	No	No	3200	DISABLED	DISABLED	2,4	2,6
D-2779	on request	16	126	No	No	3200	DISABLED	DISABLED	2,5	2,8
D-2738	on request	8	88	No	No	2933	DISABLED	DISABLED	2,5	3

Note: DTR applies to these processors. See user guide for further information

Block Diagram

COMh-sdID (E2)



Variants

PART NO.	CPU	1/2.5 GbE	SOC-LAN	DIMM	NVMe	OP. TEMPERATURE
HSD01-0000-96-2	D-2796NT	I226-LM	8x LAN ports	4	no	0 °C to +60 °C
HSD01-0000-76-2	D-2776NT	I226-LM	8x LAN ports	4	no	0 °C to +60 °C
HSD01-0000-53-2	D-2753NT	I226-LM	8x LAN ports	4	no	0 °C to +60 °C
HSD02-0000-96-1	D-2796TE	I226-IT	8x LAN ports	4	no	-40 °C to +80 °C
HSD02-0000-75-1	D-2775TE	I226-IT	8x LAN ports	4	no	-40 °C to +80 °C
HSD02-0000-52-1	D-2752TER	I226-IT	8x LAN ports	4	no	-40 °C to +80 °C

Please contact your sales representative for other CPU versions or LAN configurations
Please contact tech support for custom UEFI firmware

ARTICLE	PART NO.	DESCRIPTION
COM-HPC/SERVER EVAL-CARRIER	HST01-0000-10-0	Eval-Carrier with 10-mm stack-up connector

Cooling

ARTICLE	PART NO.	DESCRIPTION
COMh-sdID (E2) HSP THREADED	HSD01-0000-99-0	COMh-sdID (E2) heatspreader threaded
COMh-sdID (E2) HSP THROUGH HOLE	HSD01-0000-99-1	COMh-sdID (E2) heatspreader through hole
COMh SIZE D ACTIVE UNI COOLER (W/O HSP)	HSD99-0000-99-0	COM-HPC Size D Universal Active Cooler for Heatspreader Mounting (160 x 100 x 46 mm)
COMh SIZE D PASSIVE UNI COOLER (W/O HSP)	HSD99-0000-99-1	COM-HPC Size D Universal Passive Cooler for Heatspreader Mounting (160 x 100 x 46 mm)
COOLING COMh-sdID (E2): ADAPTER	HSD01-0000-99-A	Cooling Solution for COMh-sdID (E2), adapter for a standard LGA115x cooling solution. To be used with HSD01-0000-99-B & HSD01-0000-99-C
COOLING COMh-sdID (E2): BACKPLATE	HSD01-0000-99-B	Cooling Solution for COMh-sdID (E2), backplate To be used with HSD01-0000-99-A & HSD01-0000-99-C
COOLING COMh-sdID (E2): COOLER	HSD01-0000-99-C	Cooling Solution for COMh-sdID (E2), LGA115x cooler To be used with HSD01-0000-99-A & HSD01-0000-99-B

Memory

PART NO.	DESCRIPTION	SIZE	ECC/NON-ECC	OP. TEMPERATURE
97100-0832-SDID	DDR4-3200 RDIMM	8 GByte	ECC	0 °C to +60 °C
97100-1632-SDID	DDR4-3200 RDIMM	16 GByte	ECC	0 °C to +60 °C
97100-3232-SDID	DDR4-3200 RDIMM	32 GByte	ECC	0 °C to +60 °C
97100-6432-SDID	DDR4-3200 RDIMM	64 GByte	ECC	0 °C to +60 °C
97101-0832-SDID	DDR4-3200 RDIMM	8 GByte	ECC	-40 °C to +85 °C
97101-1632-SDID	DDR4-3200 RDIMM	16 GByte	ECC	-40 °C to +85 °C
97101-3232-SDID	DDR4-3200 RDIMM	32 GByte	ECC	-40 °C to +85 °C
97101-6432-SDID	DDR4-3200 RDIMM	64 GByte	ECC	-40 °C to +85 °C
97102-1232-SDID	DDR4-3200 LRDIMM	128 GByte	ECC	0 °C to +60 °C
97103-1232-SDID	DDR4-3200 LRDIMM	128 GByte	ECC	-40 °C to +85 °C

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